

Technical Data Sheet



ASSEMBLY MATERIALS

Product Type: No Clean Solder Paste

Product Name: F640 SAC405-87D30

Description

F640 SAC405-87D30 solder paste is a lead free no clean solder paste that promotes outstanding wetting and minimizes soldering defects. The F 640 flux system is specifically optimized for lead free alloys. This formula provides superior performance on a variety of surface finishes and leaves behind a clear residue.

Key Benefits

- Outstanding wetting
- Exceptional print to print consistency
- Min. 8 hours tack and work life

Compliant Products

- Flux SF 64
- Solder Wire W640

Applications

- Dispensing

Product Code and Alloy

Product Code					Powder Properties		
Paste	Alloy	Metal Content	*Viscosity	Powder Type	Particle Size	Alloy	Melting Point
F640	SAC405	87%	D	3	25 – 45 µm	Sn95.5/Ag4/Cu0.5	217 °C

*D = Dispense grade M = Print grade H = Print grade, high L = Dipping/Jetting grade, Low

Flux Activity

Activity Level (J-STD 004)	ISO 9454-1 {DIN EN 29454-1}	Classification
RELO	1.2.2.C	No Clean/ Solvent Clean

Halogen Content

Halogen-Containing

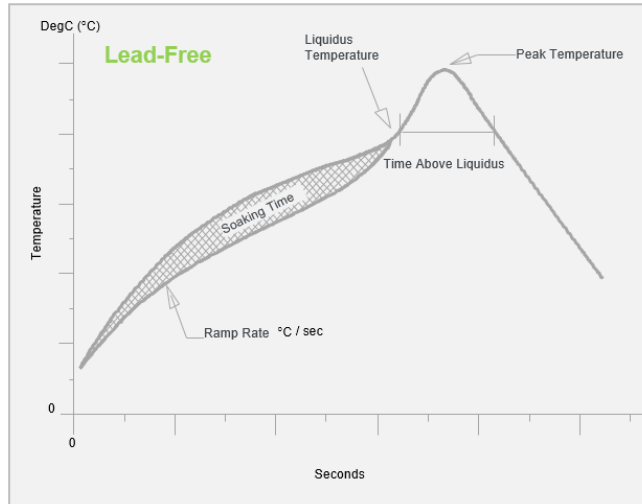
Tolerances: Cl or Br > 900 ppm, total > 1500 ppm;
measured according to BS EN 14582

Testing

Copper Mirror Test (J-STD 004) Passed	Silver Chromate Test (J-STD 004) Passed
Copper Plate Corrosion Test (J-STD 004) Passed	Surface Insulation Resistance (SIR) Test (J-STD 004) (Bellcore GR78) Passed

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Recommended Reflow Profile



* Graph not drawn to scale

Recommended Profile	
Average Ramp Rate	1 – 3 °C/s
Peak Temperature	15 °C (min) – 40 °C (max) above Melting Temperature
Time above liquidus	45 – 90 s
Reflow Atmosphere Type 3 – 5	Reflow in Air or in N ₂ with < 2000 ppm O ₂

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Cleaning Instructions

After reflow flux residues may remain on the circuit and do not need to be washed. For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used – see separate cleaning recommendations.

Storage

- Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity
- Max expiration date: please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 2 - 10 °C
- Store cartridges with tip pointing downwards

Paste Preparation

- Remove paste from fridge: Before opening the package, leave paste for at least 4 hours (depending on jar/ cartridge size) at room temperature, so that paste warms up
- Do not open jar/cartridge while paste is cold to prevent condensation
- Do not heat the paste beyond room temperature
- Before using of paste jar: To obtain uniform, stable viscosity stir paste for 1 to 2 min, using a stainless steel or chemically resistive plastic spatula
- For further information see Technical Information

Heraeus Electronics
Heraeus Deutschland GmbH & Co. KG
Heraeusstraße 12 – 14
63450 Hanau, Germany
www.heraeus-electronics.com

Americas
Phone +1 610 825 6050
electronics.americas@heraeus.com

Asia Pacific
Phone +65 6571 7677
electronics.apac@heraeus.com

China
Phone +86 21 3357 5457
electronics.china@heraeus.com

Europe, Middle East and Africa
Phone +49 6181 35 3069, +49 6181 35 3627
electronics.emea@heraeus.com